ABSTRACT

A thermally conductive film adhesive composition including an epoxy resin (A), an epoxy resin curing agent (B), a polymer component (C), a polyhedral alumina filler (D), and a silane coupling agent (E), wherein a percentage of the polyhedral alumina filler (D) to a total content of the epoxy resin (A), the epoxy resin curing agent (B), the polymer component (C), the polyhedral alumina filler (D), and the silane coupling agent (E) is from 20 to 70 vol%, and wherein a blending multiple of the silane coupling agent is from 1.0 to 10;

a film adhesive using the composition;

a semiconductor package; and

a producing method thereof.

(Fig. 1)